

ABSTRACT

~~The present invention provides~~ An apparatus ~~for supporting~~ supports, during a testing operation, a leadframe formed with at least one row of non-singulated semiconductor devices. The apparatus ~~comprises~~ includes a main body and a leadframe support member, and the leadframe support is formed with at least one groove for receiving semiconductor devices such that in use leads extending from ~~said~~ the semiconductor devices lie on a surface of ~~said~~ the support member. ~~The invention also relates to a system for transporting devices to and from a test probe head~~